

PMP5368_REVA BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	22nF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
2	C10, C13	470uF	Capacitor, Aluminum, SMT, 2V, 20%	7343(D)	2R5TPE470M9	Sanyo
1	C108* See Note 5	1500pF	Capacitor, Ceramic, vvV, [temp], [tol]	0805	GRM40yyyxxKvv	muRata
1	C15	22uF	Capacitor, Ceramic, 6.3V, X5R, 20%	1210	GRM32ER60J226M	Murata
1	C2	Not used	Capacitor, Ceramic, 10V, X7R, 10%	0603	Std	Std
1	C3	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
2	C4, C6	10uF	Capacitor, Ceramic, 16V, X5R, 10%	0805	Std	Std
1	C7	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	Std
1	C5	4.7uF	Capacitor, Ceramic, 25V, X5R, 20%	0805	std	std
2	C9, C12	10uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	std	std
1	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	J2	D120/4DS	Terminal Block, 4-pin, 15-A, 5.1mm	0.80 x 0.35 inch	D120/4DS	OST
1	J3	PEC03SAAN	Header, Male 3-pin, 100mil spacing	0.100 inch x 3	PEC03SAAN	Sullins
1	J4	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
1	L1	1.5uHy	Inductor, SMT, 12A, 9-milliohm	0.255 x 0.270 ir	IHLP2525EZER1R	Vishay
2	Q1, Q4	CSD17302Q5A	MOSFET, NChan, 30V, 7.3 mohms at 4.5Vgs	QFN5X6mm	CSD17302Q5A	Ti(Ciclon)
2	R1, R11	10.0K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	11.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R108* See Note 5	1	Resistor, Chip, 1/2W, 1%	2010	STD	Vishay
2	R2, R12	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	80.6k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	10	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	R5	2.37	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R6, R7	0	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	SH1	SH1	Short jumper			
3	TP1, TP2, TP5		Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 ir	5002	Keystone
4	TP3, TP4, TP7, TP9		Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 ir	5001	Keystone
2	TP6, TP8		Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 ir	5000	Keystone
1	U1	TPS51218DSC	IC, Single Synchronous Step-Down Controller	DSC-10	TPS51218DSC	TI
1	U2	TPS51103DRC	IC, Integrated LDO With Switch-over Circuit	DGS10	TPS51103DRC	TI
1	--		PCB, 2.1 In x 1.9 In x 0.063 In		HPA496 REV A	Any

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk ("**") cannot be substituted.
All other components can be substituted with equivalent MFG's components.
 5. Insert C108 & R108 in series by hand from feedthrus near Q4 pin 4 going straight to right side of C9

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